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09/615836
07/13/00

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereto:

1. Name of conveying party(ies):

Chun Hung LIN

Additional name(s) of conveying party(ies) attached?

2. Name and address of receiving party(ies):

Name: Advanced Semiconductor Engineering, Inc.

Internal Address:

Street Address:
No.26, Chin 3rd Road, Nantze Export Processing Zone,
Kaoshiung

City:
State or Area:
Zip/Postal Code:
Country: TAIWAN, R.O.C.

Additional name(s) & address(es) attached?

3. Nature of conveyance:

X Assignment
__ Merger
__ Security Agreement
__ Change of Name
__ Other

Execution Date: March 29 2000

4. Application number(s) or patent number(s):

If the document is being filed together with a new application, the execution date of the application is: March 29, 2000

A. Patent Application No(s).

B. Patent No(s). 09 615836

Additional numbers attached?

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: LOWE HAUPTMAN GOPSTEIN GILMAN & BERNER

Internal Address:

Street Address: 1700 Diagonal Road, Suite 310
City: Alexandria State: VA ZIP: 22314

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41) $40.00

Is enclosed

8. Deposit account number: 07-1337

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Benjamin J. Hauptman
Registration No. 29,310

Signature

July 13, 2000
Date

Total number of pages comprising cover sheet: 1

CMB No. 0851-0011 (exp. 4/94)

Docket No.:

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

(1) Chun Hung LIN
(2)
(3)
(4)
(5)
(6)

who have made a certain new and useful invention, hereby sell, assign and transfer unto

Advanced Semiconductor Engineering, Inc.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

MULTICHIP MODULE HAVING STACKED CHIP ARRANGEMENT

(a) for which an application for United States Letters Patent was filed on ______________, and identified by United States Serial No. ________________; or

(b) for which an application for United States Letters Patent was executed on May 29, 2000,

and the undersigned hereby authorize and request the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside our signatures:

INVENTORS	DATE SIGNED
1) Signature: Chun Hung LIN Name: Chun Hung LIN	May 29, 2000
2) Signature: Name:	
3) Signature: Name:	
4) Signature: Name:	
5) Signature: Name:	
6) Signature: Name	

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